

# FR30M

## High Efficiency RFID Dry Inlay Bonder

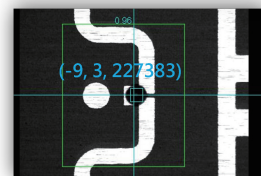
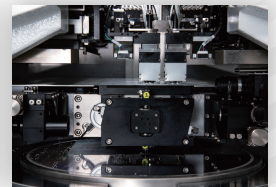
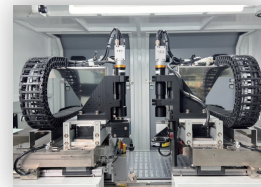


### ABOUT FR30M

- UPH of Bonding: 30,000ea/hour
- Bonding Accuracy:  $\pm 30\mu\text{m}$
- Bonding Theta (Rotation):  $\pm 2^\circ$
- Hot stamping unit: 40 sets
- Temperature : Ambient to  $300^\circ\text{C} \pm 5^\circ\text{C}$
- Web width : 40-340mm (Max.)
- Capable of multi-rows for production, testing, slitting and winding

### FEATURES

- Web outer diameter software calculation
- Single Jetting valve device and Double Multi-Bonding Arms module
- Real time jetting monitoring and control function
- Jetting monitoring function before bonding
- Real time bonding monitoring
- Hot stamping module programmable control
- Auto takes tag backside pictures for QC operator visual inspection
- Jetting monitoring after testing



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Item	Detail Item	Specification	Remark
Main Features	Power	Single Phase, AC220V, 14A / 18A	
	Air supply	0.55Mpa	Consumption: 200L/min
	Vacuum supply	-90kpa	Consumption: 50L/min
	Machine dimensions (mm · W x D x H)	12000 (L) x 1400 (D) x 2310 (H)	The length of machine is including to operation space (input spooler and output spooler). The height of machine is including to indication light tower.
	Machine total weight (kg)	7800	Estimation
	UPH of Bonding	30,000ea/hour	Depends on product requirement
	Bonding Accuracy (um · X / Y direction)	±30	
	Bonding Theta (Rotation) ( ° )	±2.0	
Web	Web width (mm)	40 ~ 340 (Max.)	
	Outer diameter of input and output reel	90 ~ 450	
	Antenna pitch (mm)	15.875 (Min.)	[Multi row ] X-Pitch: 15.875mm (Min.) Y-Pitch: 35.00mm (Min.)
	Web Material	PET · Paper	
Wafer	Chip size (mm)	0.3x0.3 ~ 2.0x2.0	
	Wafer size (inch)	8 / 12	
	Wafer type	STD Metal Frame	
Un-winding (Input Spooler)	Web tension range (Kg)	0.1 ~ 1.0	
Dispensor	Adhesive	ACP	
	CCD motion mode	Programmable control	
Bonding	Bonding force (g)	20 ~ 200	Programmable control
	CCD motion mode	Programmable control	
Wafer Table	Extension range (mm)	13 (Max.)	
	Needle module	Single Needle	Apply to smaller chip size only.
Hot stamping	Pressing force (g)	60 ~ 450	Programmable control
	Temperature range (°C)	Ambient to 300°C Max.	
	Curing time (sec)	According to material performance	Following to process parameter condition.
	Hot stamping unit (sets)	40 sets Max.	
	CCD motion mode	Programmable control	
Testing	RFID tag type	HF / UHF	
Winding (Output Spooler)	Rewinding reel	2	
	Receiving tension (N)	3 ~ 10	
	Slitting unit (ea)	9 (Max.)	
	Slitting accuracy (mm)	±0.50	

ALL SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE.